

### **Ultra-Low Capacitance TVS Diode**

 ESD / transient protection of high-speed data lines exceeding

IEC61000-4-2 (ESD): ±20 kV (air / contact)

IEC61000-4-4 (EFT): 2.5 kV/50 A (5/50 ns)

IEC61000-4-5 (surge): 3 A (8/20 μs)

 Extremely small form factor down to 0.62 x 0.32 x 0.31 mm<sup>3</sup>

Max. working voltage: 3.3 V

• Very low reverse current: < 1 nA typ.

• Extremely low capacitance: 0.4 pF typ.

 Very low clamping voltage: 12 V typ. at positive transients, 4 V typ. at negative transients

• Very low series inductance down to 0.2 nH typ.

Pb-free (RoHS compliant) package

Qualified according AEC Q101

#### **Applications**

- USB 2.0, 10/100/1000 Ethernet, Firewire, DVI, HDMI, S-ATA
- Mobile communication
- Consumer products (STB, MP3, DVD, DSC...)
- LCD displays, camera
- Notebooks and desktop computers, peripherals





### ESD3V3U1U-02LS ESD3V3U1U-02LRH

Туре	Package	Configuration	Marking
ESD3V3U1U-02LRH	TSLP-2-7	1 line, uni-directional	E3
ESD3V3U1U-02LS	TSSLP-2-1	1 line, uni-directional	Z





**Maximum Ratings** at  $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Value	Unit
ESD (air / contact) discharge <sup>1)</sup>	V <sub>ESD</sub>	20	kV
Peak pulse current $(t_p = 8 / 20 \mu s)^2)$	I <sub>pp</sub>	3	Α
Operating temperature range	$T_{op}$	-55125	°C
Storage temperature	$T_{\rm stg}$	-65150	

**Electrical Characteristics** at  $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics	•				
Reverse working voltage	$V_{RWM}$	-	-	3.3	V
Breakdown voltage	$V_{(BR)}$	5	-	-	
$I_{(BR)} = 1 \text{ mA}$ , from pin 1 to 2					
Reverse current	I <sub>R</sub>	-	< 1	50	nA
$V_{R}$ = 3.3 V, from pin 1 to 2					
Clamping voltage	$V_{CL}$				V
$I_{PP} = 1 \text{ A}, t_p = 8/20  \mu\text{s}^2$ , from pin 1 to 2		-	10	13	
$I_{PP} = 3 \text{ A}, t_p = 8/20 \ \mu\text{s}^{2}$ , from pin 1 to 2		-	12	15	
Forward clamping voltage	V <sub>FC</sub>				
$I_{PP} = 1 \text{ A}, t_p = 8/20 \ \mu\text{s}^{2}$ , from pin 2 to 1		-	2	4	
$I_{PP} = 3 \text{ A}, t_p = 8/20  \mu\text{s}^{2)}, \text{ from pin 2 to 1}$		-	4	6	
Line capacitance <sup>3)</sup>	C <sub>T</sub>	-	0.4	0.6	pF
$V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$					
Series inductance	L <sub>S</sub>				nH
ESD3V3U1U-02LS		-	0.2	-	
ESD3V3U1U-02LRH		-	0.4	_	

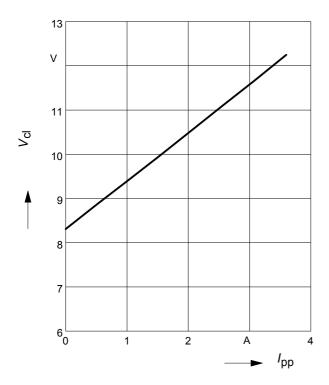
 $<sup>^{1}</sup>V_{\text{ESD}}$  according to IEC61000-4-2

 $<sup>^2</sup>I_{\rm pp}$  according to IEC61000-4-5

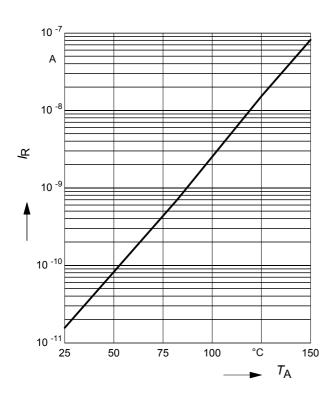
<sup>&</sup>lt;sup>3</sup>Total capacitance line to ground



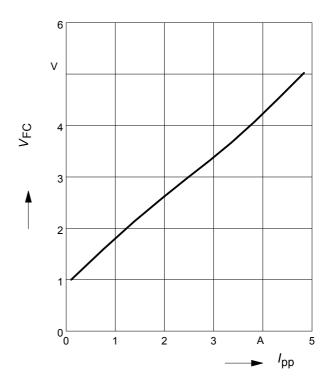
Clamping voltage,  $V_{cl} = f(I_{pp})$  $t_p = 8 / 20 \mu s$ , from pin 1 to 2



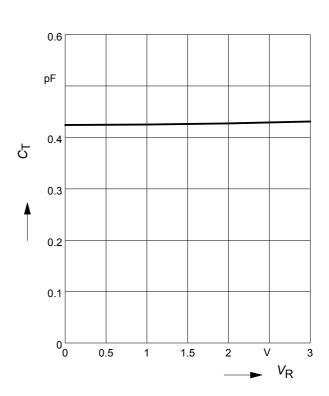
Reverse current  $I_R = f(T_A)$  $V_R = 3.3 \text{ V}$ , from pin 1 to 2



Forward clamping voltage  $V_{FC} = f(I_{PP})$  $t_p$  = 8 / 20 µs, from pin 2 to 1



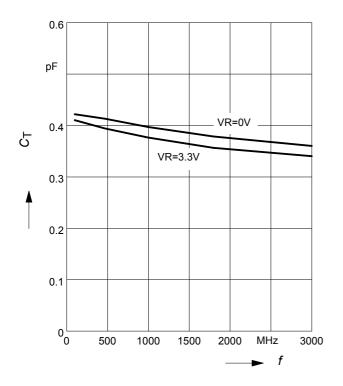
**Line capacitance**  $C_T = f(V_R)$ f = 1 MHz, from pin 1 to 2





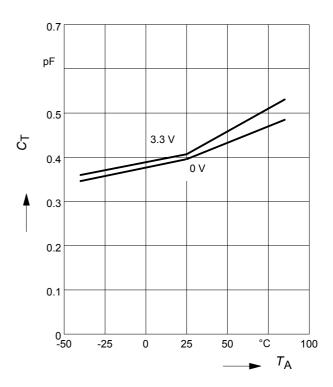
# **Line capacitance** $C_T = f$ (f)

 $V_{\mathsf{R}}$  = parameter, from pin 1 to 2



# Line capacitance $C_T = f(T_A)$

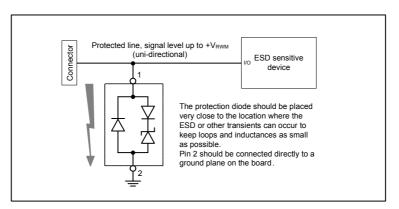
 $V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$ 





### Application example ESD3V3U1U...

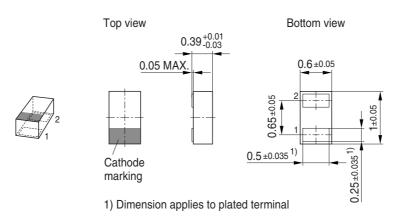
1-channel, uni-directional



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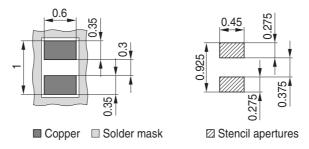


### Package Outline

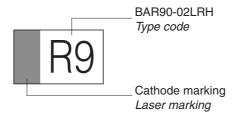


#### Foot Print

For board assembly information please refer to Infineon website "Packages"

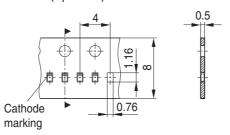


### Marking Layout (Example)



### Standard Packing

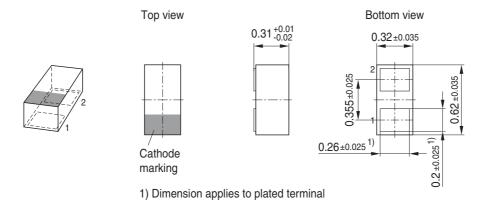
Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)



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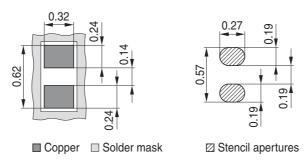


### Package Outline

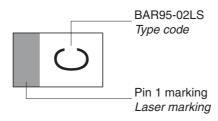


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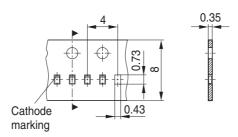


### Marking Layout



## Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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